

Technical Data Sheet Top Phototransistor PT67-21C/L606/TR8(GH)

Features

- Fast response time
- High photo sensitivity
- Small junction capacitance
- Compatible with infrared and vapor phase reflow solder process.
- Pb free
- The product itself will remain within RoHS compliant version.



Description

• PT67-21C/L606/TR8(GH) is a high speed silicon NPN epitaxial planar phototransistor in a compact surface-mountable package. It's compatible with automatic placement equipment and can withstand IR reflow, vapor phase reflow , and wave solder processes.

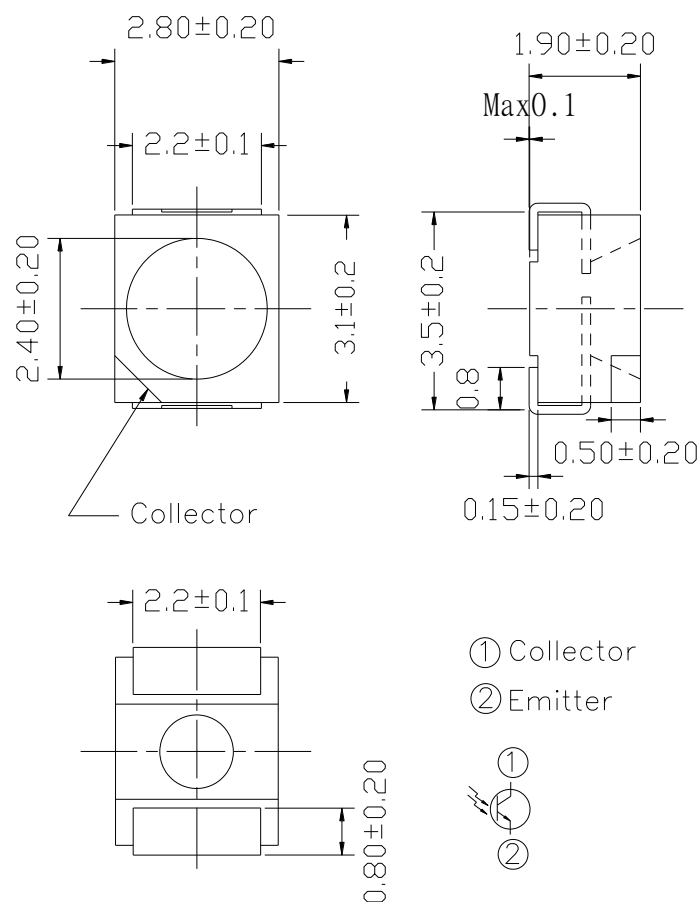
Applications

- Miniature switch
- Counters and sorter
- Position sensor
- Infrared applied system
- Encoder

Device Selection Guide

Device No.	Chip Material	Lens Color
PT67-21C/L606/TR8(GH)	Silicon	Water clear

Package Dimensions



Notes: 1.All dimensions are in millimeters
2.Tolerances unless dimensions $\pm 0.1\text{mm}$

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Rating	Unit
Collector-Emitter Voltage	V_{CEO}	30	V
Collector Current	I_C	20	mA
Operating Temperature	T_{opr}	$-25 \sim +85$	$^\circ\text{C}$
Storage Temperature *1	T_{stg}	$-40 \sim +85$	$^\circ\text{C}$
Soldering Temperature	T_{sol}	260	$^\circ\text{C}$
Power Dissipation at(or below) 25 $^\circ\text{C}$ Free Air Temperature	P_c	75	mW

Notes: *1:Soldering time ≤ 5 seconds.

Electro-Optical Characteristics (Ta=25°C)

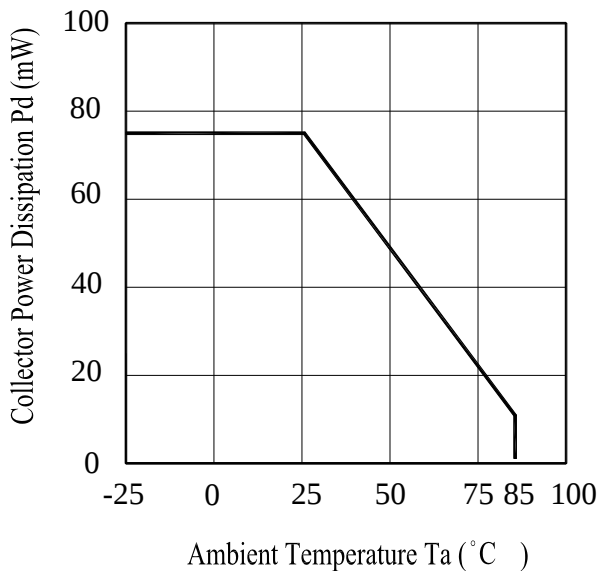
Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Rang Of Spectral Bandwidth	$\lambda_{0.5}$	400	---	1100	nm	---
Wavelength Of Peak Sensitivity	λ_p	---	940	---	nm	---
Collector-Emitter Breakdown Voltage	BV_{CEO}	30	---	---	V	$I_C=100\mu A$ $E_e=0mW/cm^2$
Emitter-Collector Breakdown Voltage	BV_{ECO}	5	---	---	V	$I_E=100\mu A$ $E_e=0mW/cm^2$
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	---	---	0.4	V	$I_C=1mA$ $E_e=1mW/cm^2$
Collector Dark Current	I_{CEO}	---	---	500	nA	$V_{CE}=20V$ $E_e=0mW/cm^2$
On State Collector Current	$I_{C(ON)}$	2.0	2.3	6.0	mA	$V_{CE}=5V$ $E_e=1mW/cm^2$
View Angle	$2\theta_{1/2}$	--	120	--	deg	$V_R = 5V$
Rise Time	t_r	---	15	---	μS	$V_{CE}=5V$ $I_C=1mA$ $R_L=1000\Omega$
Fall Time	t_f	---	15	---		

Rank:

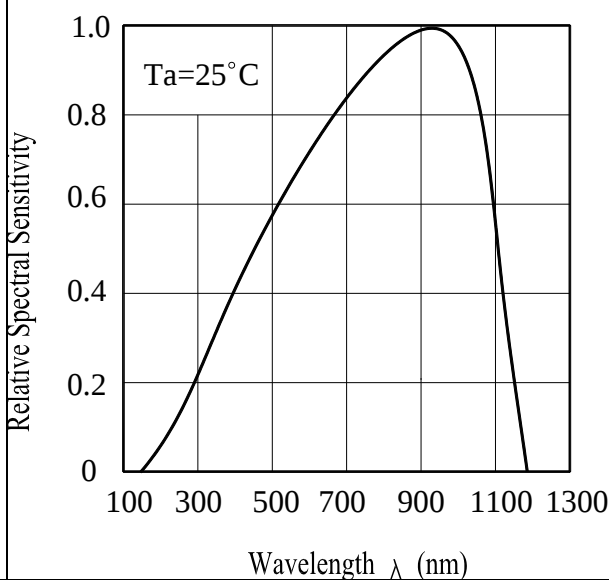
Rank	Test Condition	Min	Max	Unit
1	$V_{CE}=5V$ $E_e=1mW/cm^2$	2.0	3.5	mA
2		3.0	6.0	

Typical Electrical/Optical/Characteristics Curves

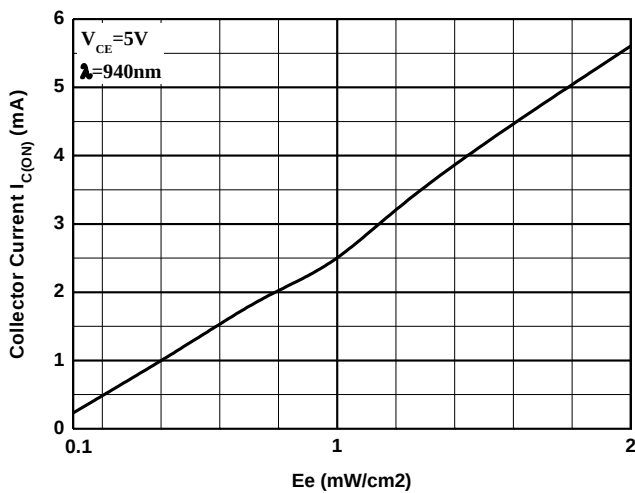
Collector Power Dissipation vs. Ambient Temperature



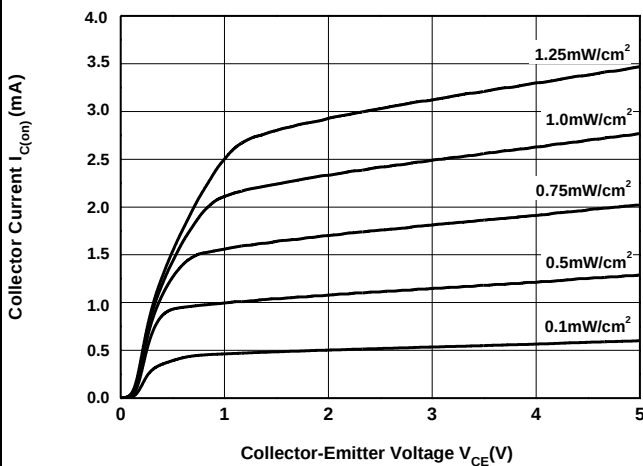
Spectral Sensitivity



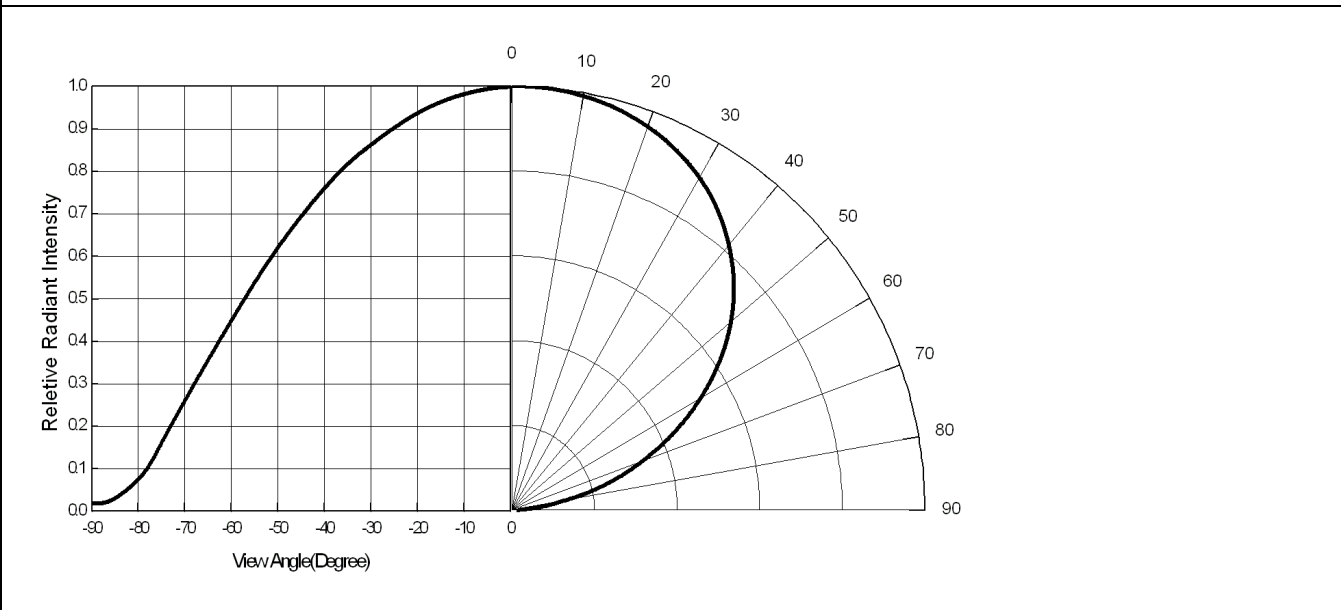
Collector Current vs. Irradiance



Collector Current vs. Collector-Emitter Voltage



Relative Light Current vs. Angular Displacement



Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package, the Phototransistor should be kept at 30°C or less and 90%RH or less.

2.3 The Phototransistor should be used within a year.

2.4 After opening the package, the Phototransistor should be kept at 30°C or less and 60%RH or less.

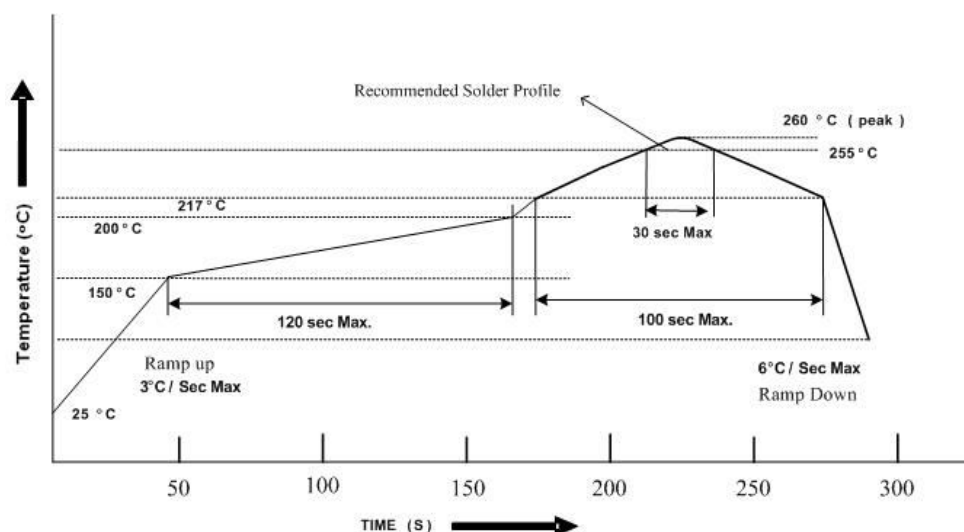
2.5 The Phototransistor should be used within 72 hours (3 days) after opening the package

2.6 If the moisture absorbent material (silica gel) has faded away or the Phototransistor have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for Min. Min. 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the Phototransistor during heating.

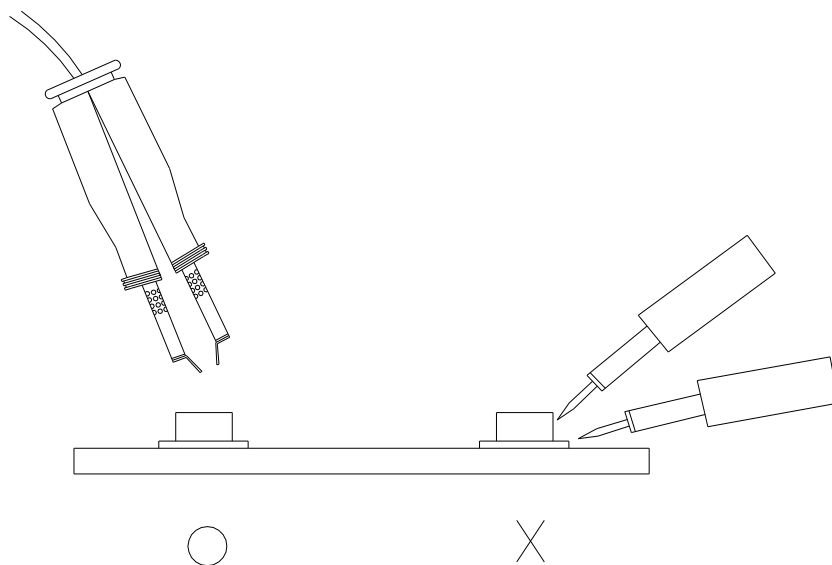
3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

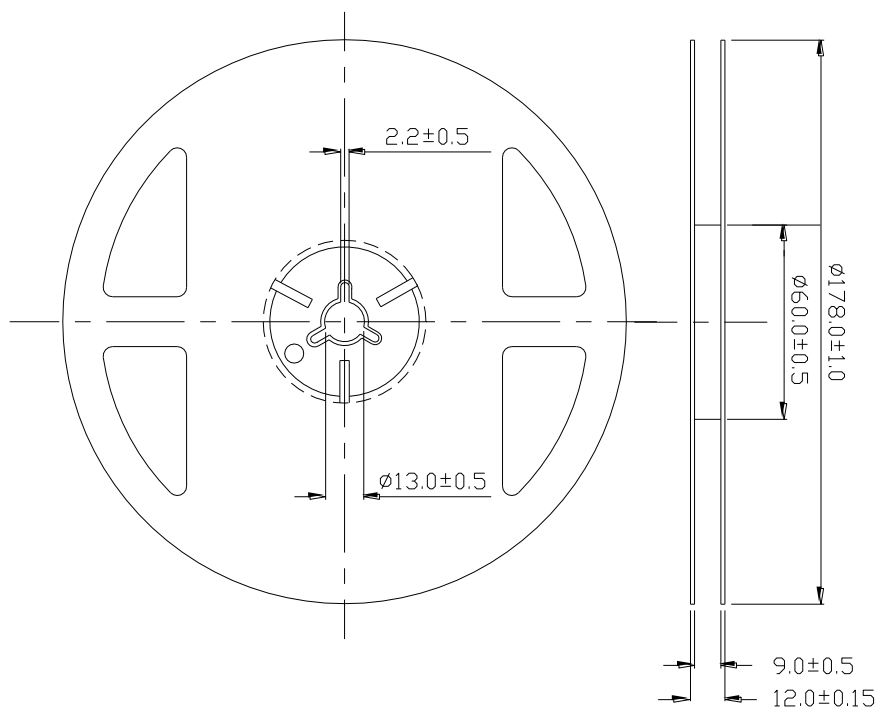
Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the Phototransistor have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the Phototransistor will or will not be damaged by repairing.

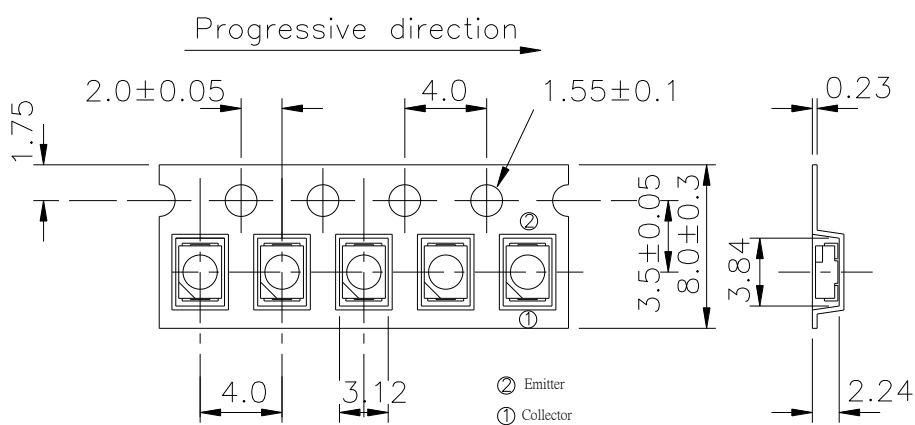


Package Dimensions



Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$, Unit = mm

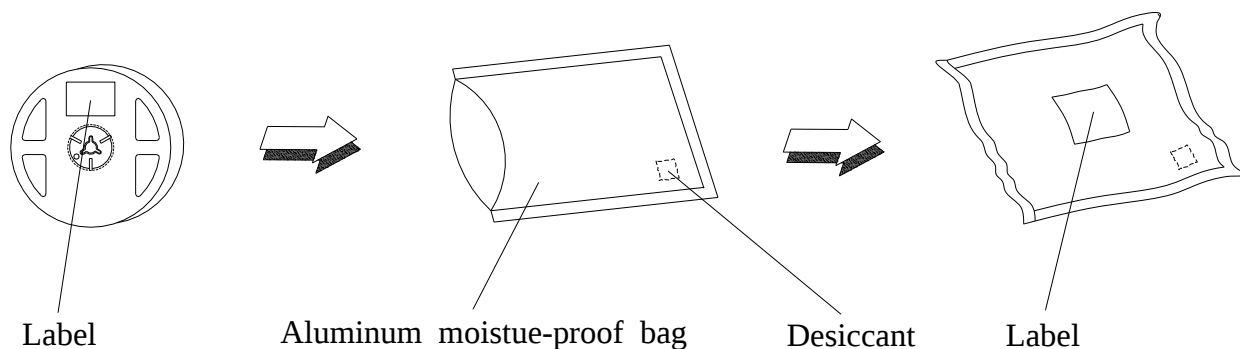
Carrier Tape Dimensions: (Quantity: 2000pcs/reel)



TOLERANCES UNLESS DIMENSION ± 0.1
ANGLE ± 0.5
UNIT: mm

Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$, Unit = mm

Packing Procedure



Label Form Specification

The label form includes the following fields and logos:

- EVERLIGHT logo
- RoHS logo
- CPN : XXXXXXXXXXXX
- P/N : XXXXXXXXXXXX
- XXXXXXXXXXXXXXXX
- QTY : XXX
- CAT : XXX
- HUE : XXX
- REF : XXX
- LOT NO : XXXXXXXXXXXX
- Reference : XXXXXXXX

CPN: Customer's Production Number
P/N : Production Number
QTY: Packing Quantity
CAT: Ranks
HUE: Peak Wavelength
REF: Reference
LOT No: Lot Number
MADE IN TAIWAN: Production Place

Notes

1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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